

FIG. 1 (PRIOR ART)

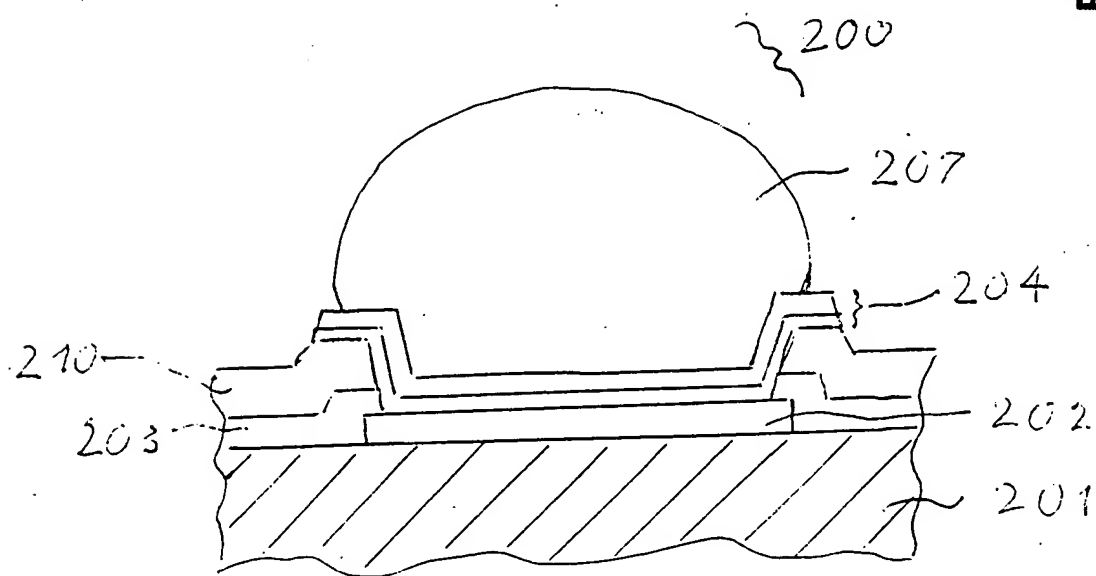


FIG. 2 (PRIOR ART)

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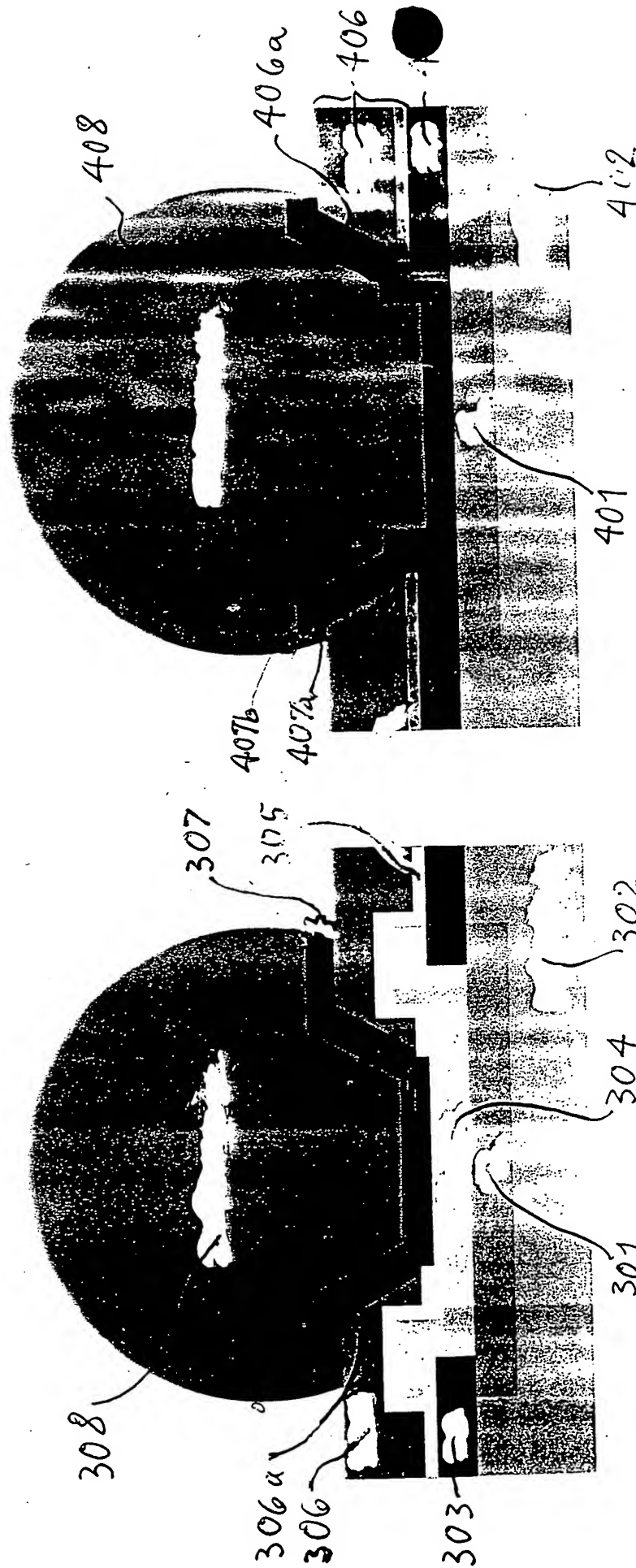


FIG. 4.
(PRIOR ART)

FIG. 3
(PRIOR ART)

FIG. 5

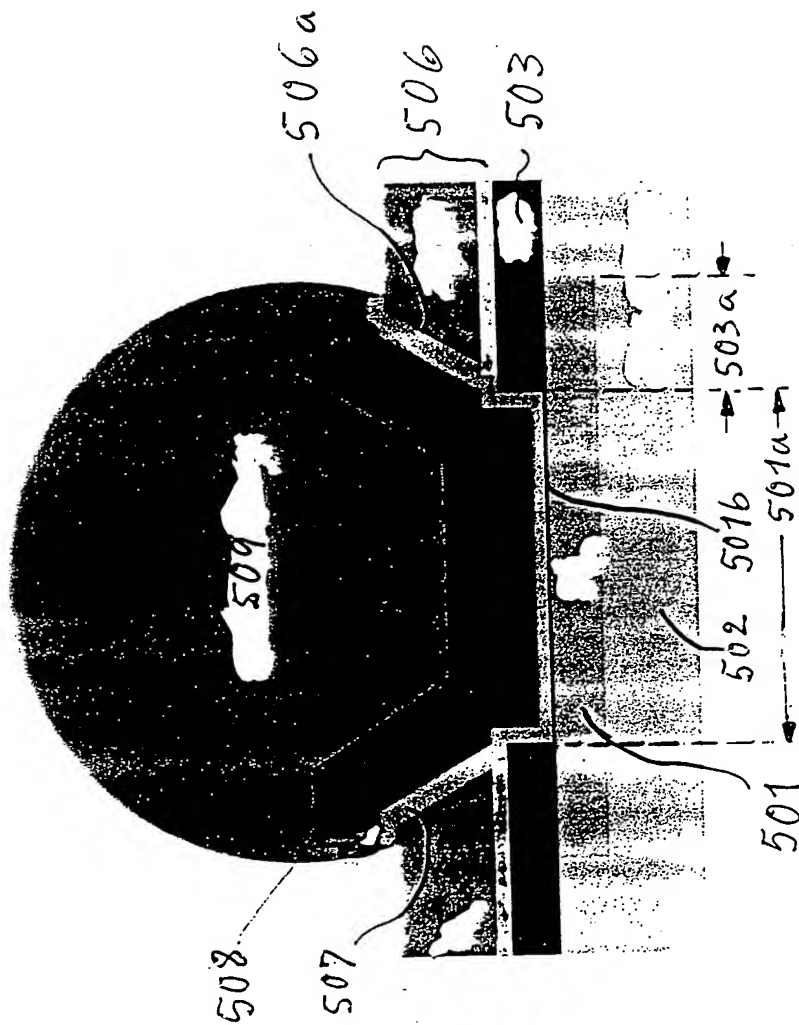


FIG. 5

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FIG. 6: Process Flow
for Direct Bumping on Copper Pads

